



GaAs-based Spin-polarized photocathode research at Cornell

Matthew Andorf



The Bright Beams Lab

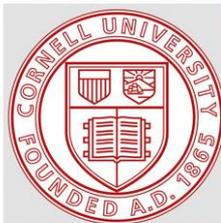
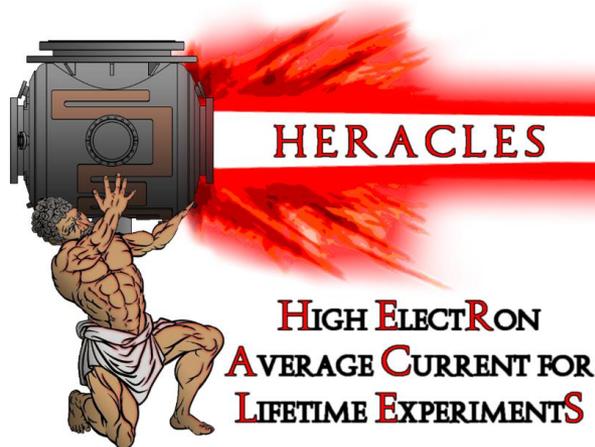
Acknowledgements to:

NP-DOE DE-SC0023517

HEP-DOE DE-SC0021002

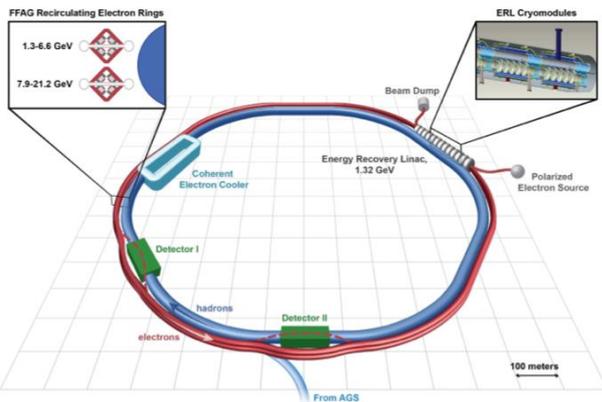
NFS PHY-1549132 CBB

- Ivan Bazarov
- Jared Maxson
- Adam Bartnik
- Alice Galdi (now @U. of Salerno)
- **Sam Levenson (graduate student)**
- **Mark Reamon (undergrad)**

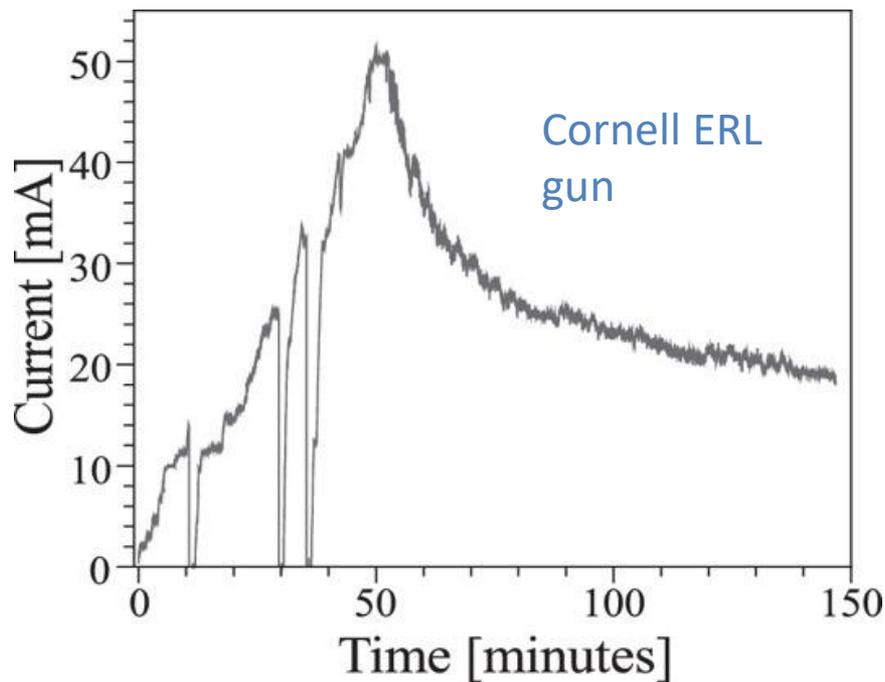
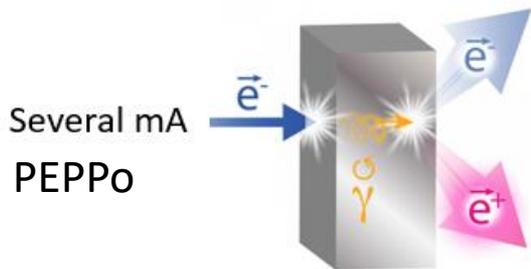
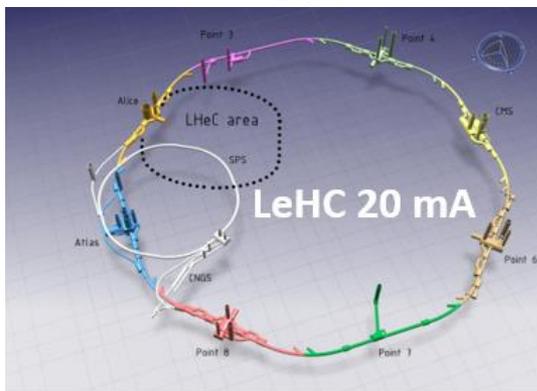




High current and spin polarization

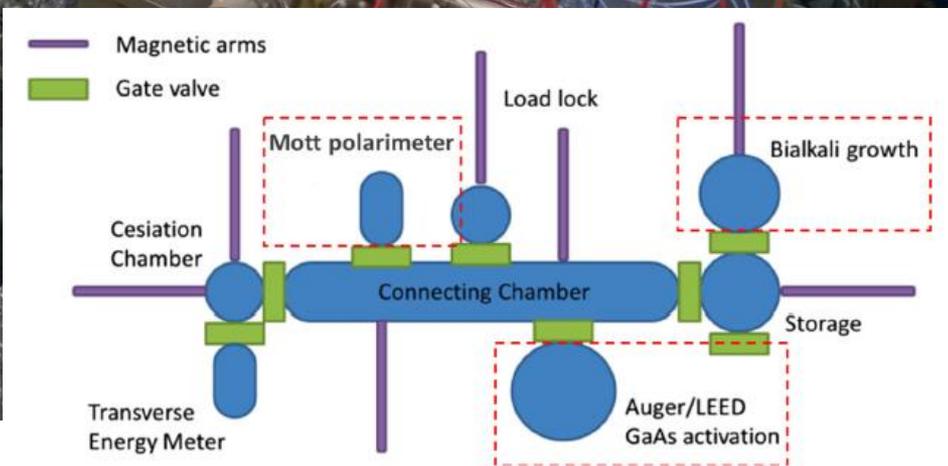
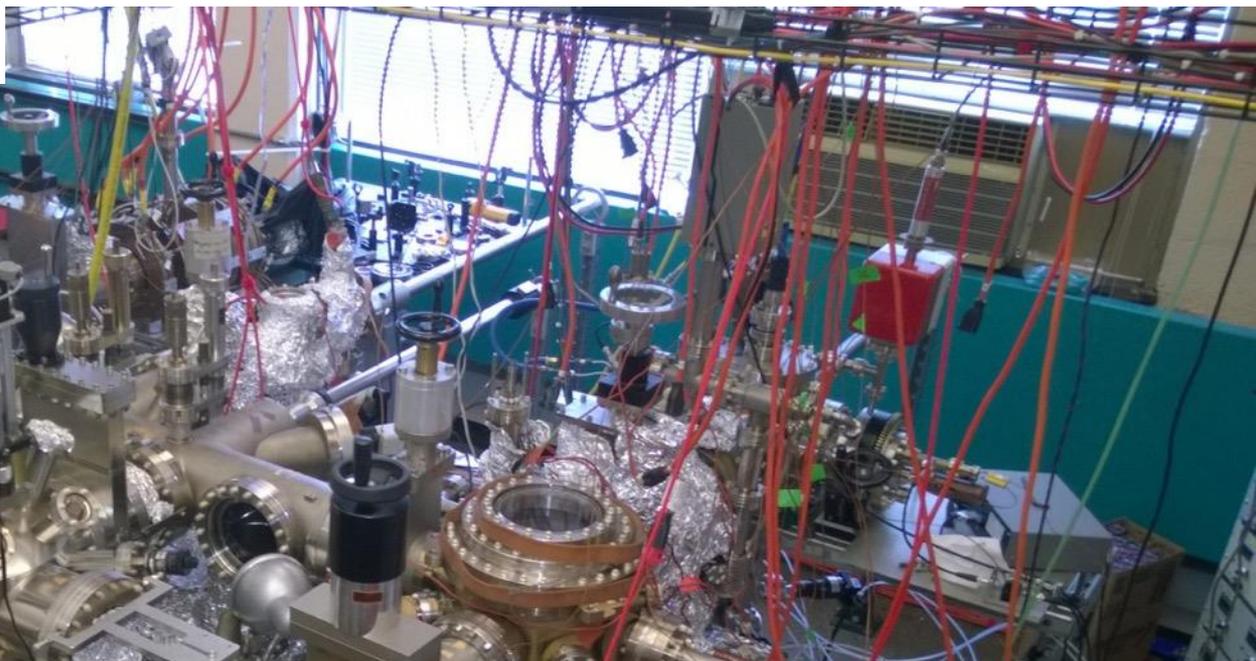
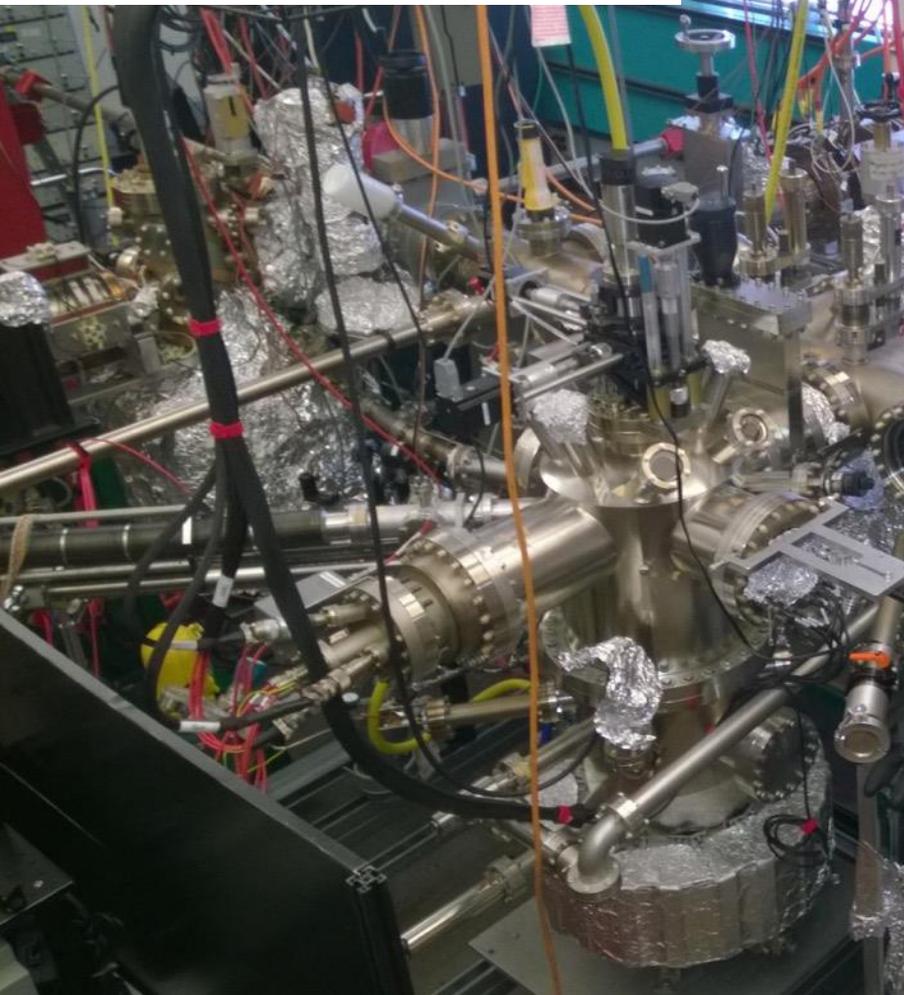


- One of the remaining challenges for photocathodes is a robust, spin-polarized electron source
- GaAs is by far the most studied spin-polarized electron source
- **Charge lifetime:** The amount of current extracted before the QE degrades by $1/e$
 - 1000 C is state of the art \rightarrow 6 hours at 50 ma!





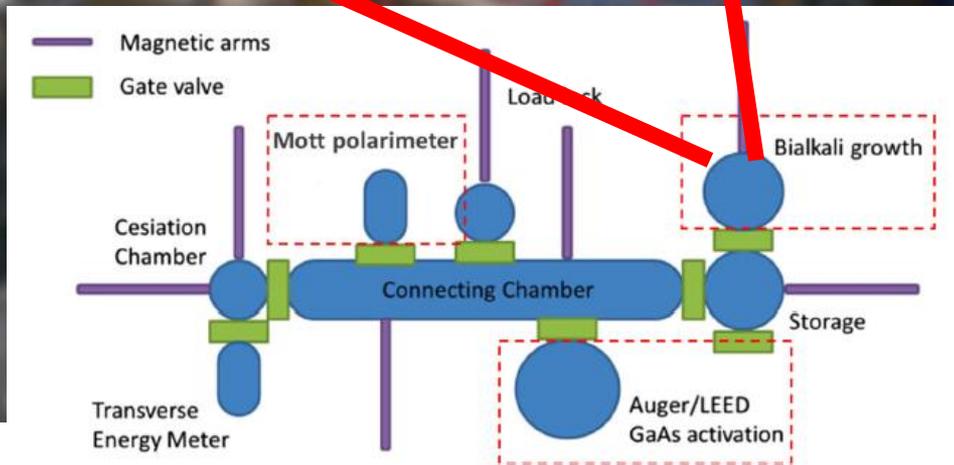
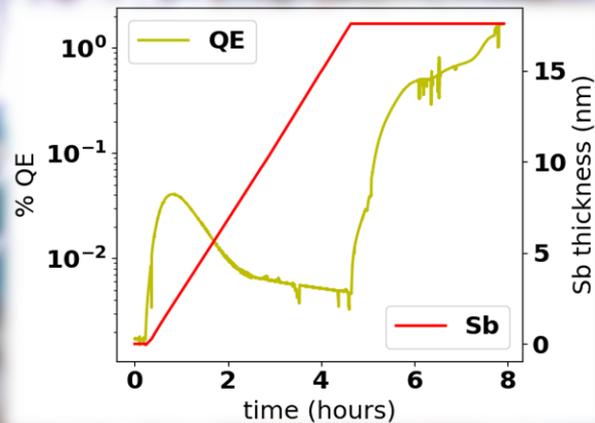
Vacuum level is below 10^{-10} Torr





Bialkali growth chamber

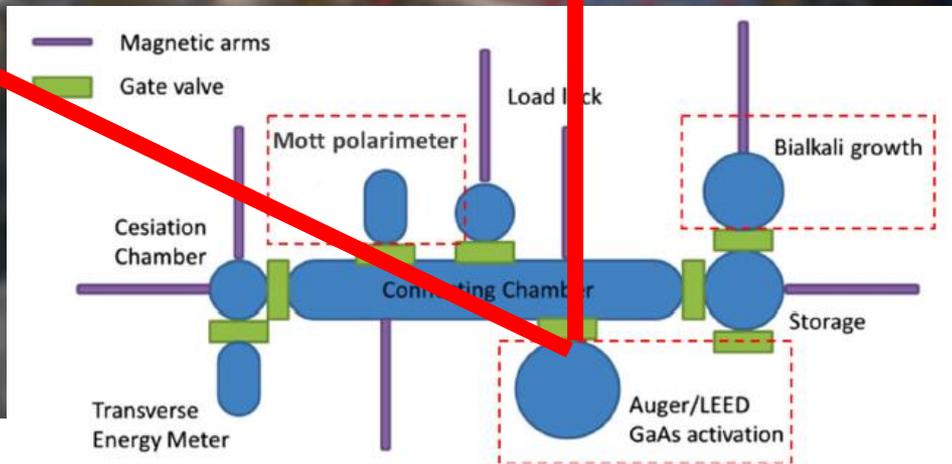
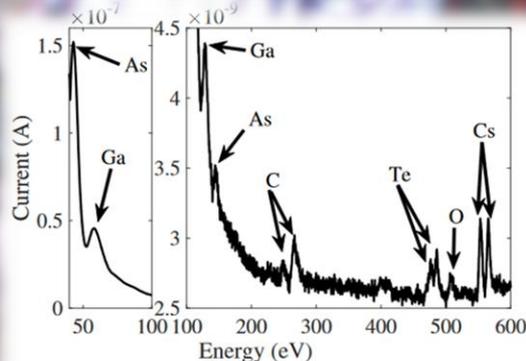
- Cs,Sb,Te sources+O₂ leak valve, thermally regulated with pneumatic valve control
- Quartz microbalance (QMB) for deposition monitoring
- Substrate heater

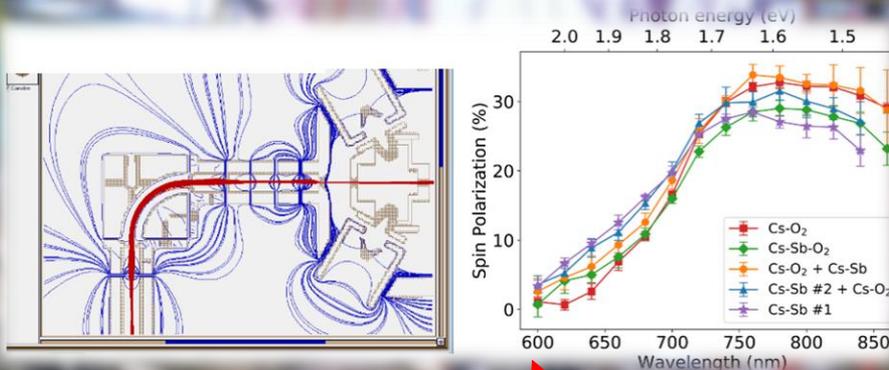




AUGER Chamber

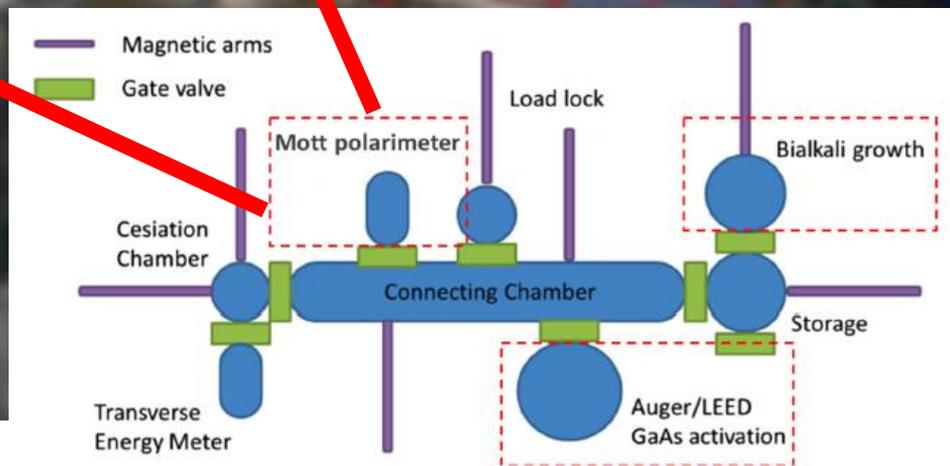
- Auger Electron Spectroscopy-To characterize surface chemistry
- Low Energy Electron Diffraction-Characterize surface crystallinity
- Cs, O₂ leak valve.
- Insulated, bias-able cathode holder





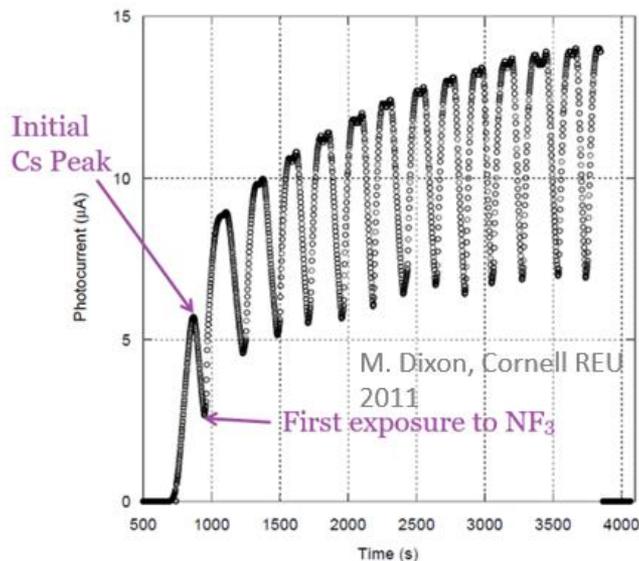
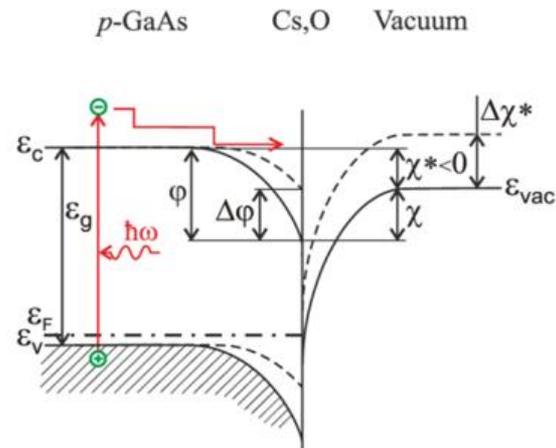
Mott polarimeter

- 20 keV target bias + Einzel lens beamline
- Tungsten scattering target
- Measure spin-polarization



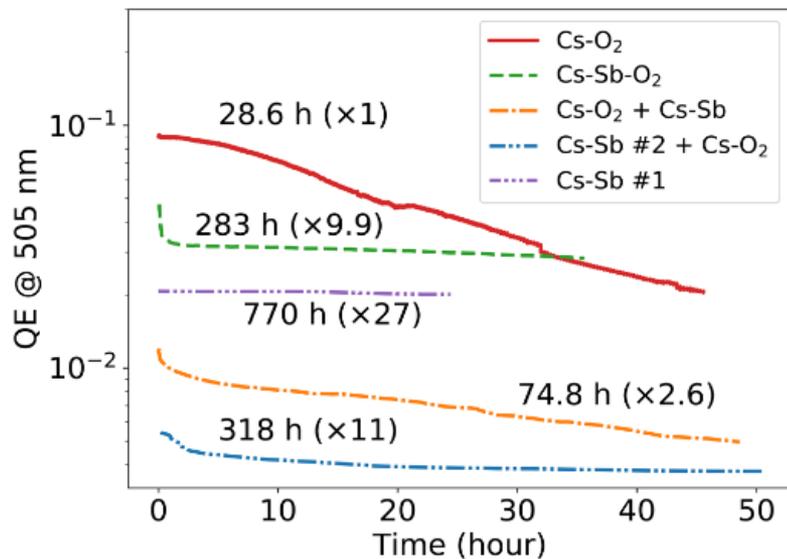
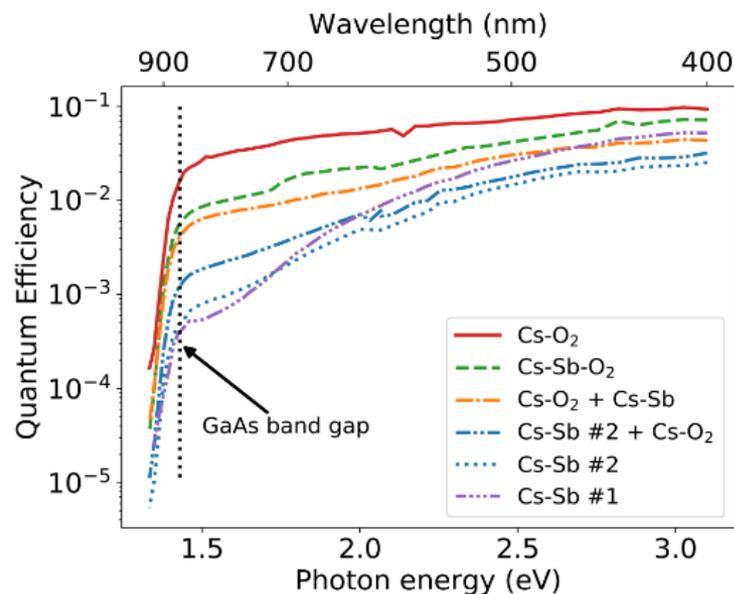
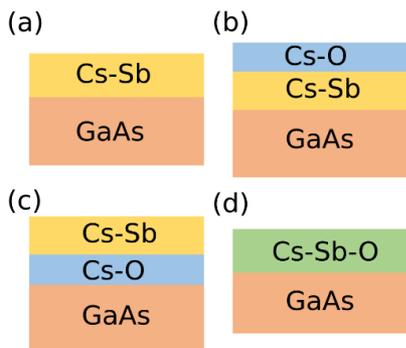
- For high QE, GaAs is “activated” to Negative Electron Affinity (NEA)
 - NEA means the bulk conduction band minimum is larger than the vacuum level
- NEA is typically achieved by depositing a monolayer of Cs-Oxidant onto the GaAs surface can be done by:
 - **Co-deposition:** Cs is deposited until QE peaks, at which point an oxidant is leaked while Cs source remains on
 - **Yo-yo method:** the cathode is over cesiated at which point the cesium source turns off. It is then exposed to an oxidant until the QE peaks, the oxidant is then turned off and cesium source back on. The cycle is repeated numerous times.
- Either O_2 and NF_3 can be used for an oxidant
- **Problem: A monolayer is a fragile thing!**
 - **Chemical poisoning:** Interaction with residual gas
 - **Ion back bombardment:** residual gas is ionized and accelerated towards the cathode

V. Khoroshilov et al. (2020). Journal of Physics: Conference Series. **1482**. 012013
DOI: [10.1088/1742-6596/1482/1/012013](https://doi.org/10.1088/1742-6596/1482/1/012013).





Sb-based recipes

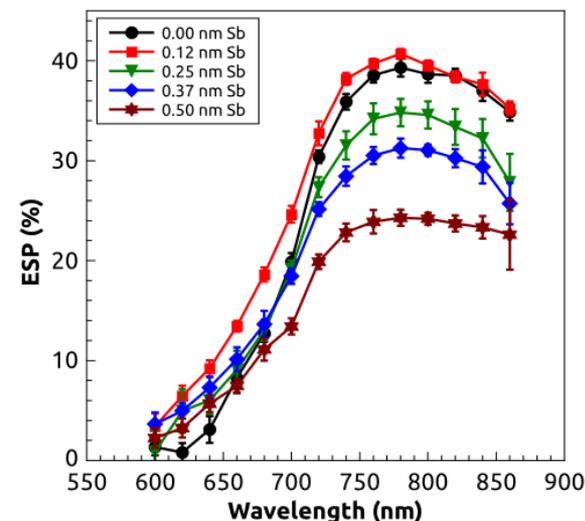
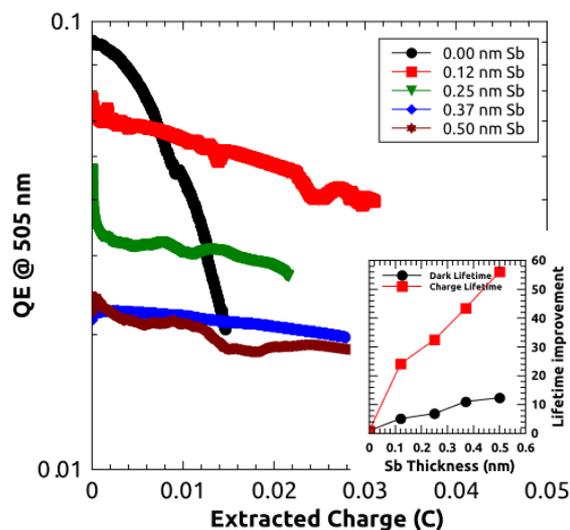
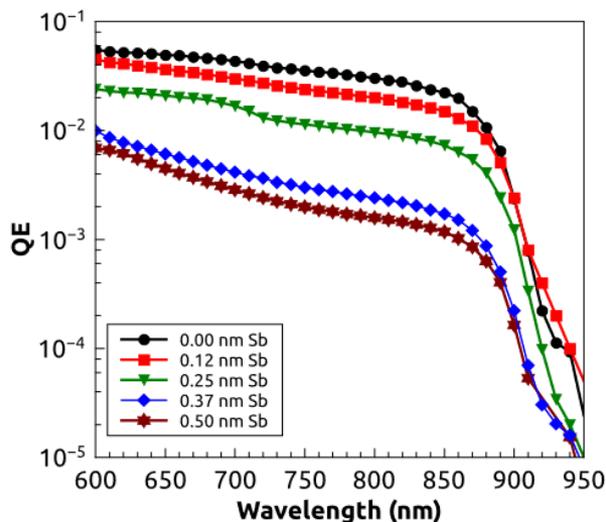


- Various activation recipes were compared to Cs-O₂
 - Overall, Cs-O₂ produced the highest QE while Cs-Sb had the worse
 - Including O₂ in the activation improved QE of Sb containing recipes
- The QE was monitored over time to determine robustness
 - All Sb activations outperformed pure Cs-O₂ and pure Cs-Sb had the longest lifetime.
- **Co-deposition of Cs-Sb-O finds a happy middle ground**
 - 10x Improved lifetime over Cs-O activation.
 - 10x improved QE over Cs-Sb activation at bandgap

Cs-O-Sb co-deposition recipe was further refined through scanning the Sb layer thickness:

- QE and electron spin-polarization decrease with Sb layer thickness
- **0.12 nm layer results in only a small QE decrease while preserving max spin-polarization!**

Cultrera et al, “Long lifetime polarized electron beam production from negative electron affinity GaAs activated with Sb-Cs-O: Trade-offs between efficiency, spin polarization, and lifetime (2020)”

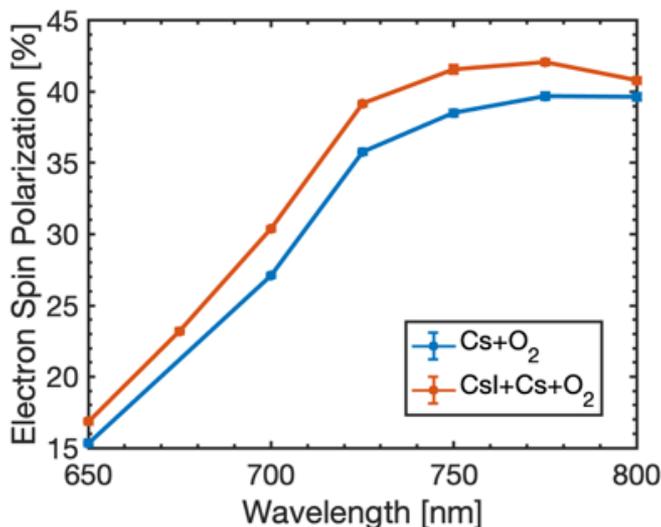
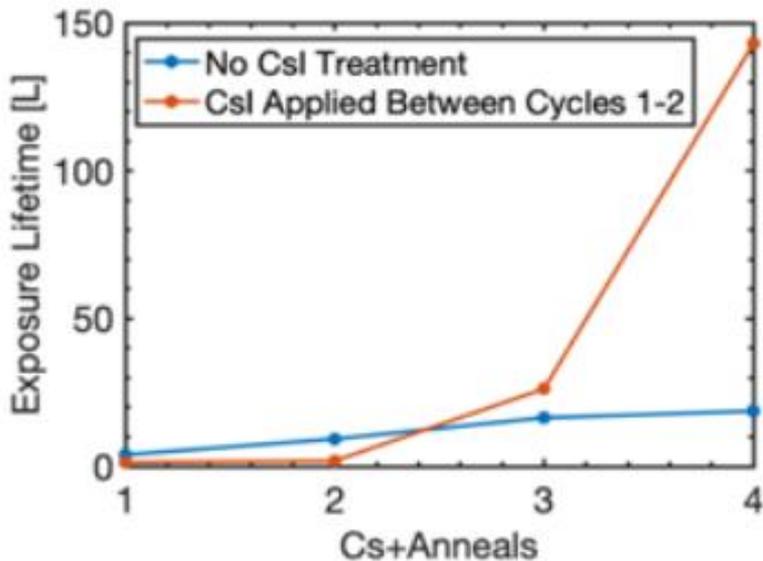
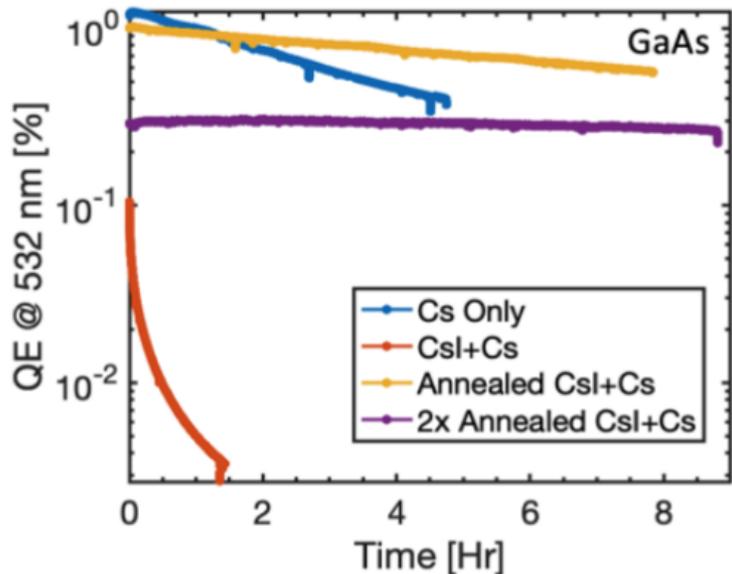




CsI surface treatment of GaAs

Use of CsI increases dark lifetime of GaAs!

- 30 second 1% HCl chemical etch+6 hour anneal at 600 C
- ~1 nm of CsI deposited on GaAs surface. Activated with Cs. Poor lifetime and QE.
- Sample annealed and re-cesiated. Lifetime improvement with comparable QE Cs only GaAs activation
- Additional anneal further improves lifetime at expense of QE
- Lifetime improvement not simply the result of additional annealing cycles



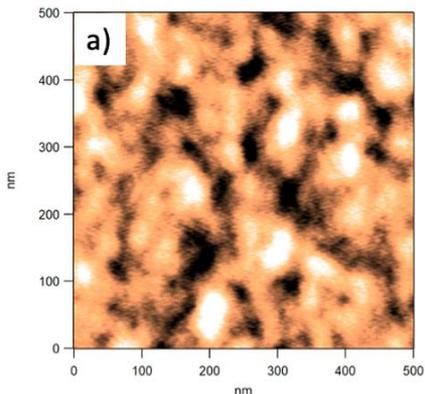
S.J. Levenson et al.
IPAC'24. MOPR82



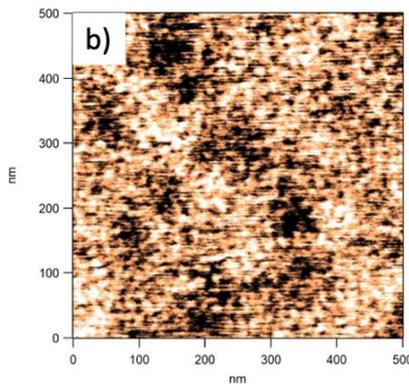
CsI surface treatment of GaAs

AFM performed at each step of
surface treatment process

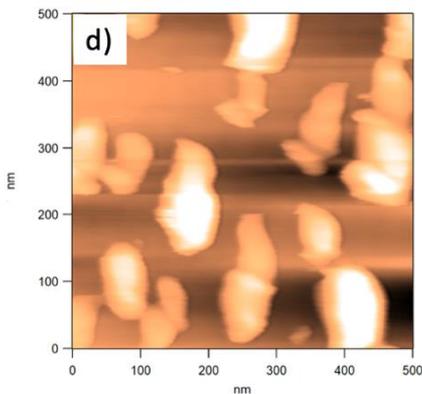
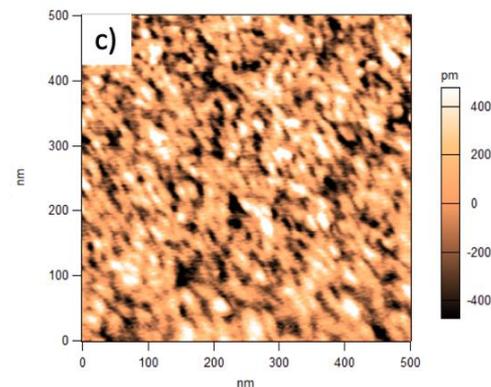
As received



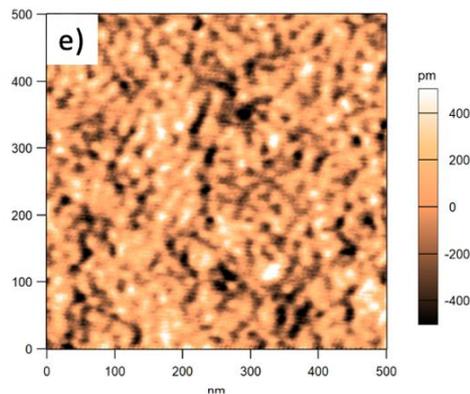
After HCl etching



600 C anneal 6 hours



After CsI deposition

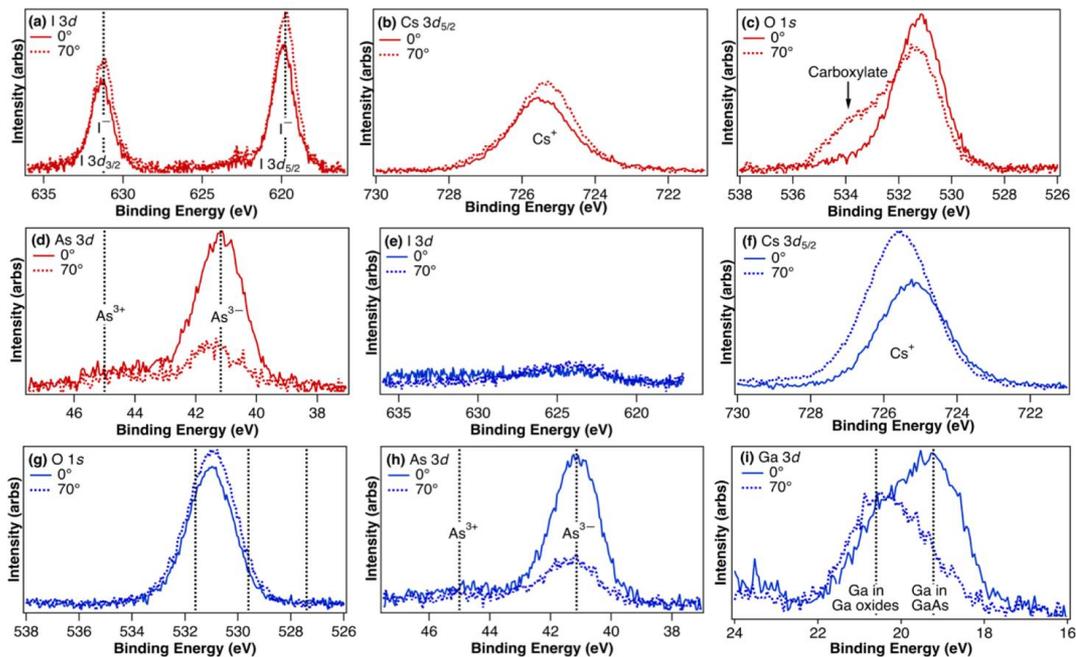


After 2nd 600 C, 6
hour anneal



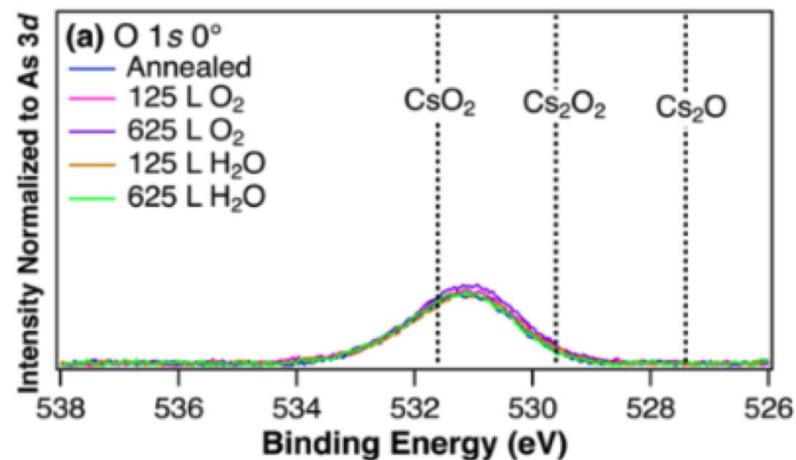
CsI surface treatment of GaAs

XPS analysis in collaboration
with Q. Zhu and M. Hines,
Cornell Chemistry
Department



XPS analysis performed on pre- and post-annealed
GaAs samples

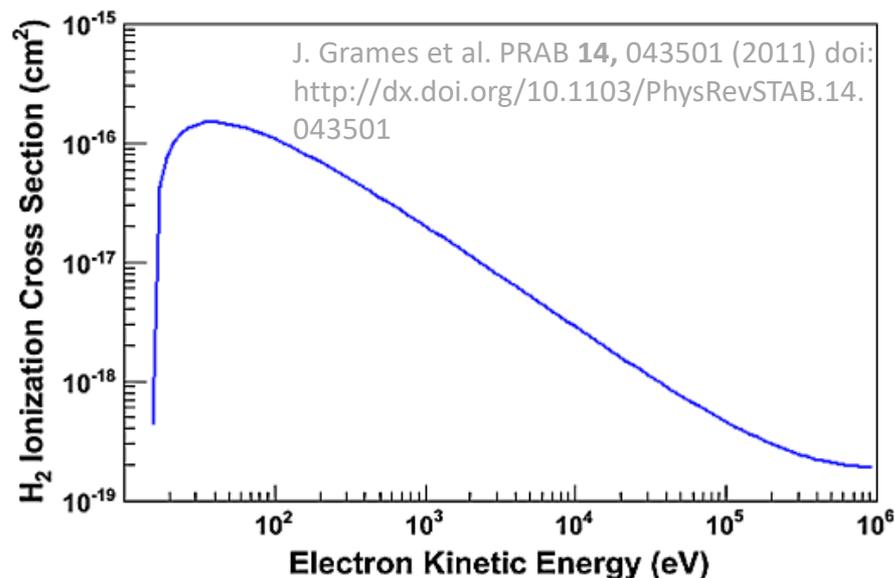
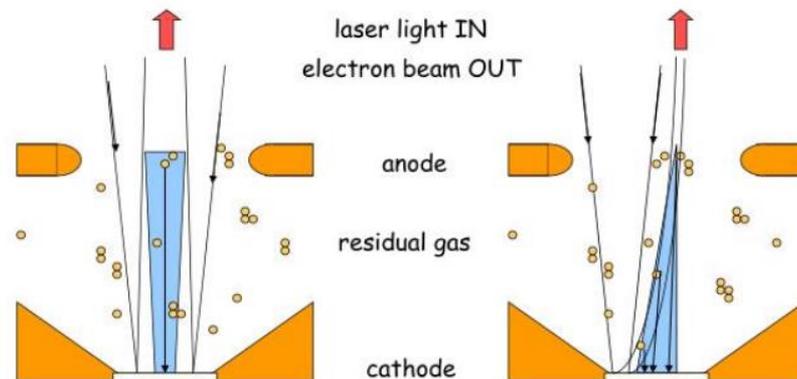
- Pre-annealed sample confirms presence of CsI
- No Iodine detected on post-annealed sample!
- Strong suppression Cs₂O



Ion back bombardment

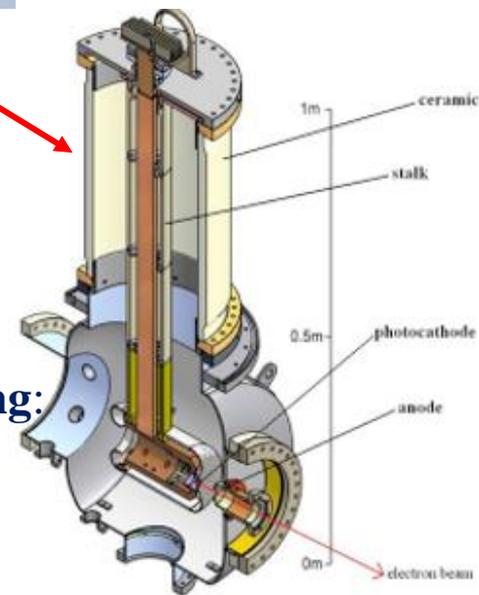
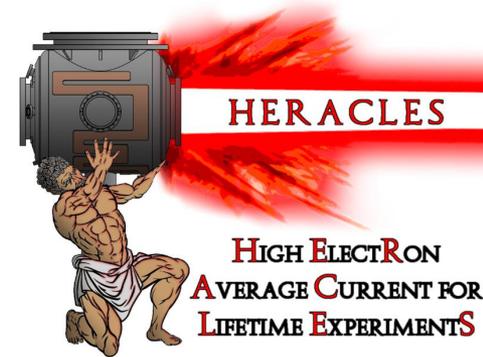
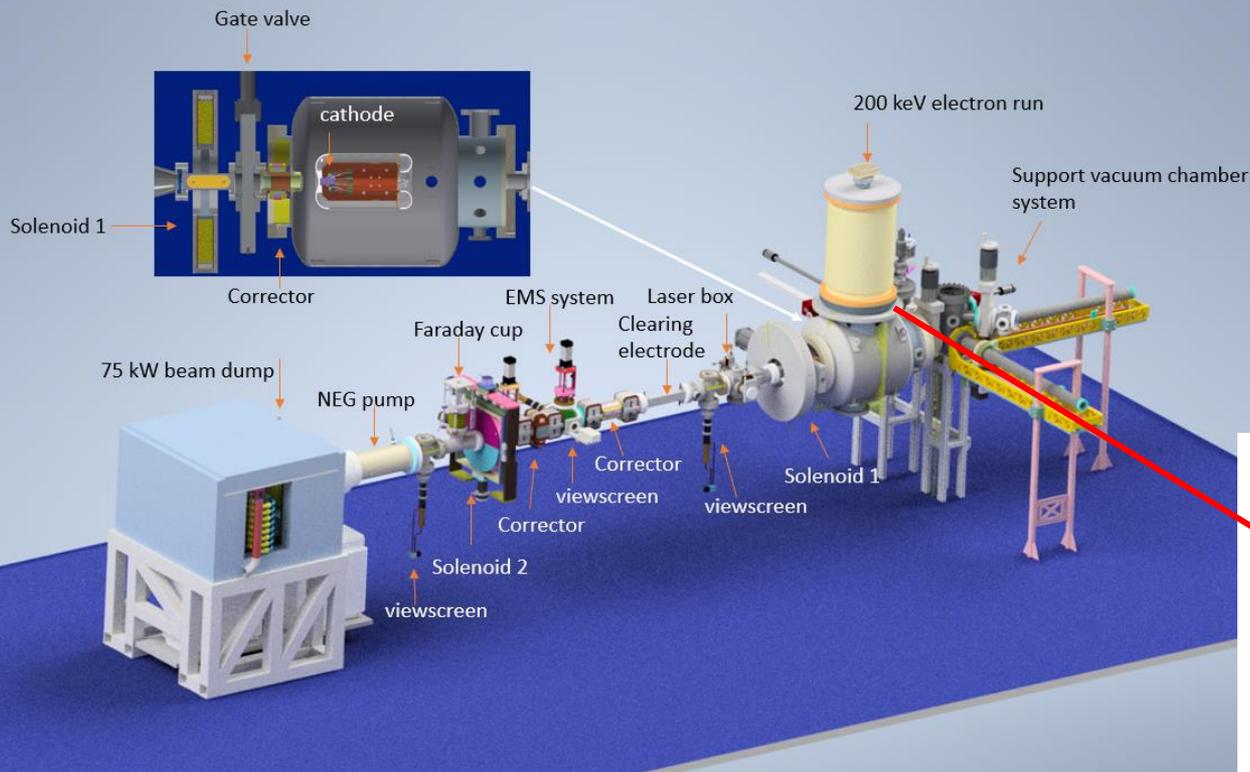
- An electron beam can ionize residual gas which will be positively charged
- Ions will be accelerated towards the cathode and cause damage
- So far, results have been in growth chamber
 - Low current (1-100 nA)
 - Low voltage (-18 V)
 - Main source of degradation comes from vacuum poisoning
- In a high voltage DC gun, induced damage from ion back bombardment is more severe
 - Lower energy ions can sputter off activation layer
 - High energy ions damage GaAs crystal structure
- **Operation at high voltage and current is critical to testing efficacy of alternative activation layers!**

Image courtesy J. Grames





The HERACLES Beamline



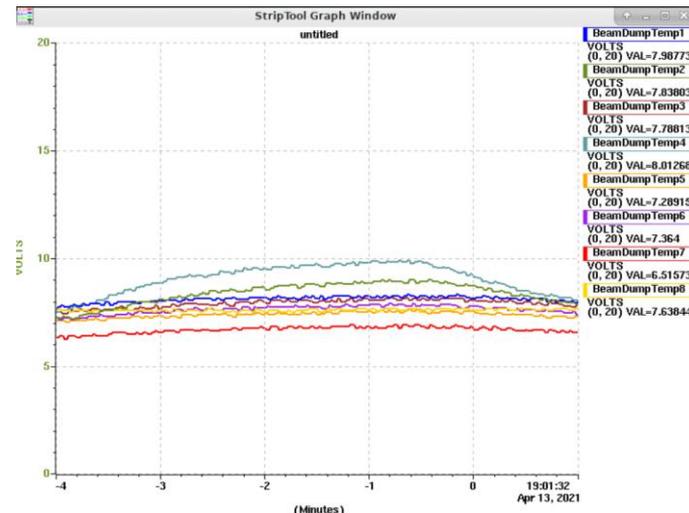
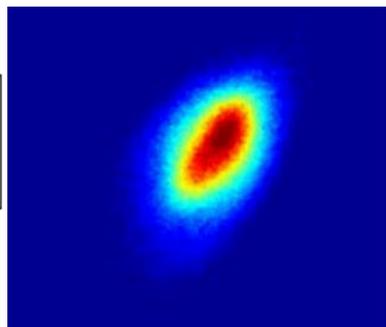
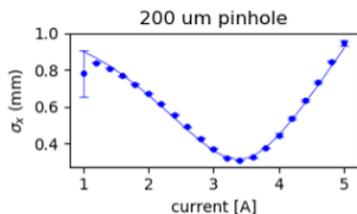
A beamline dedicated to the study of high current beam running:

- Former CU-ERL gun 200kV @ 10 mA
- Ion clearing electrodes
- 75 kW beam dump
- EPICS based control system

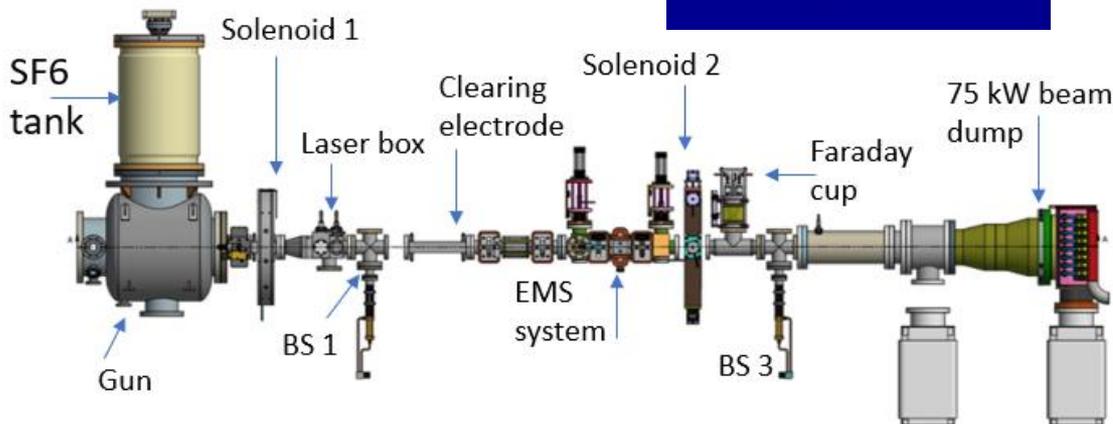


Beamline and Diagnostics

Solenoid scan characterizes cathode MTE

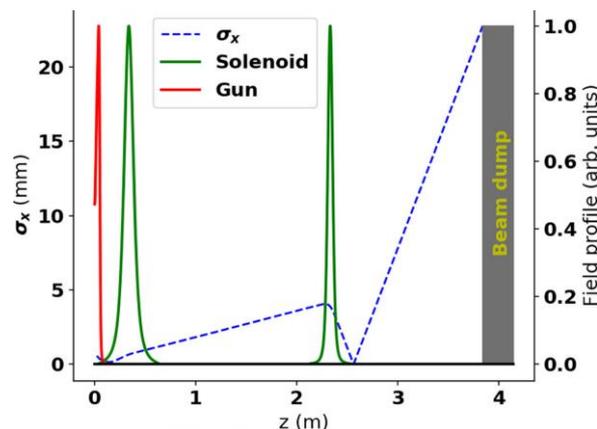


Thermal couples register beam induced temperature rise at the dump



Beamline

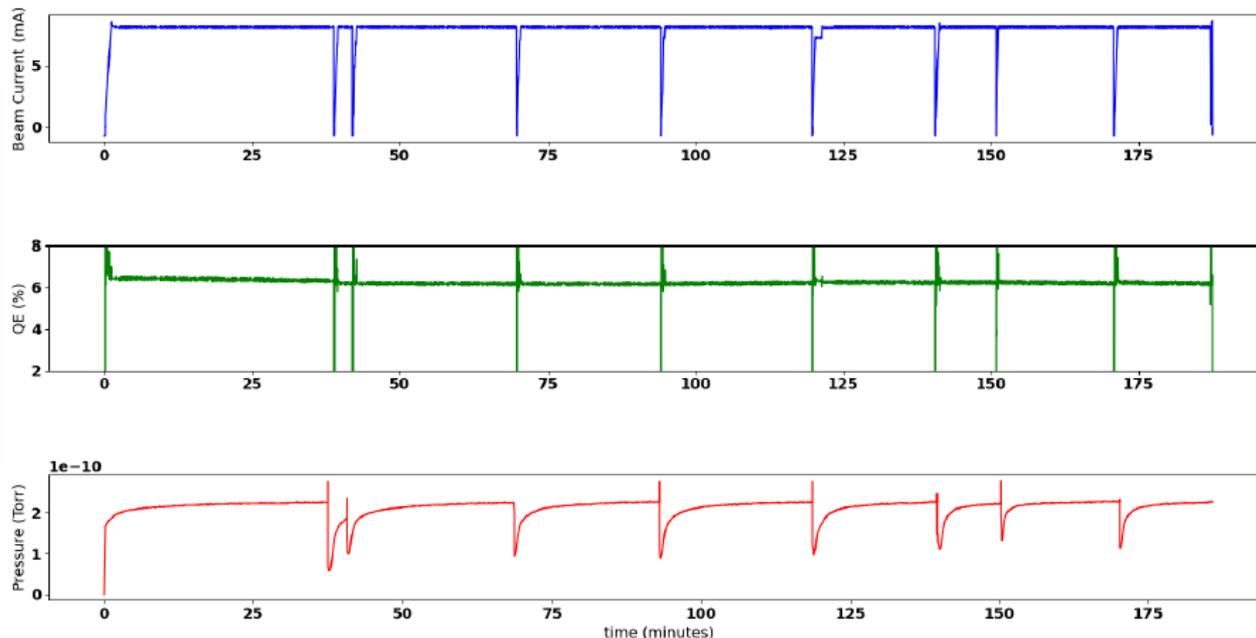
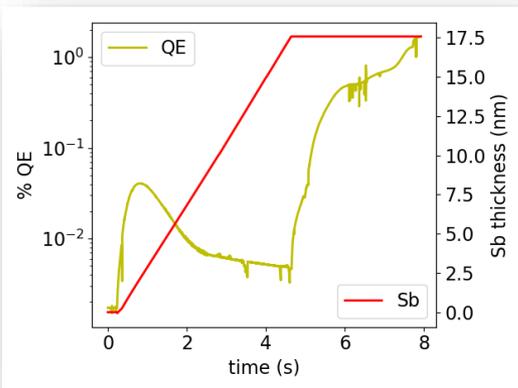
- 2 Solenoids, 3 corrector pairs (hor/vert)
- 2 clearing electrodes
- 3 screens, 1 quad detector
- 1 Faraday cup
- EMS system (not implemented)



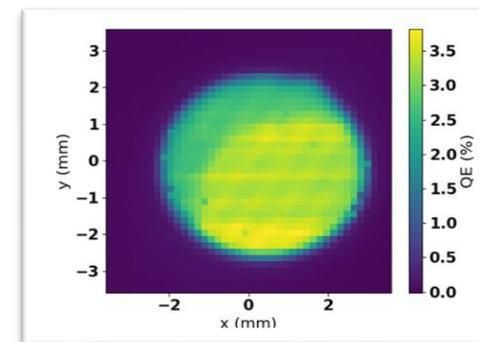
GPT simulation of fields/beam envelope



HERACLES high current performance



- Cs_3Sb cathode on stainless steel puck
- 10 mA max current, limited by radiation trips
- 8 mA constant current for 3 + hours with no significant change in cathode QE



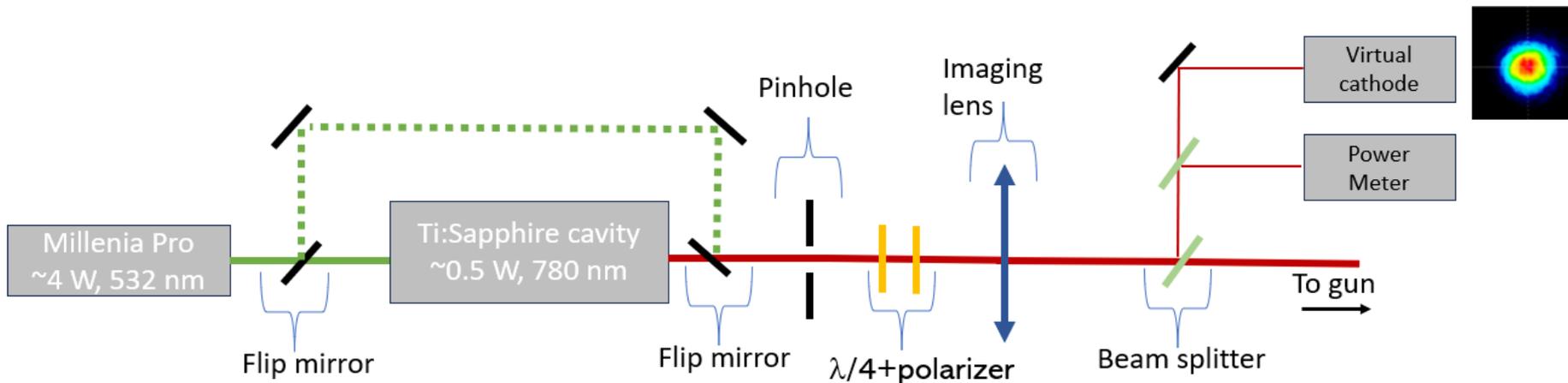
M. Andorf et al. NIMA: **1052** 168240 (2023) <https://doi.org/10.1016/j.nima.2023.168240>



HERACLES DRIVE LASER

Drive Laser for high current GaAs operation

- Ti:Sapphire oscillator: lasing at GaAs bandgap energy
- Ti:Sapphire excited with external 532 nm diode laser
- Easily switch between IR and green operation

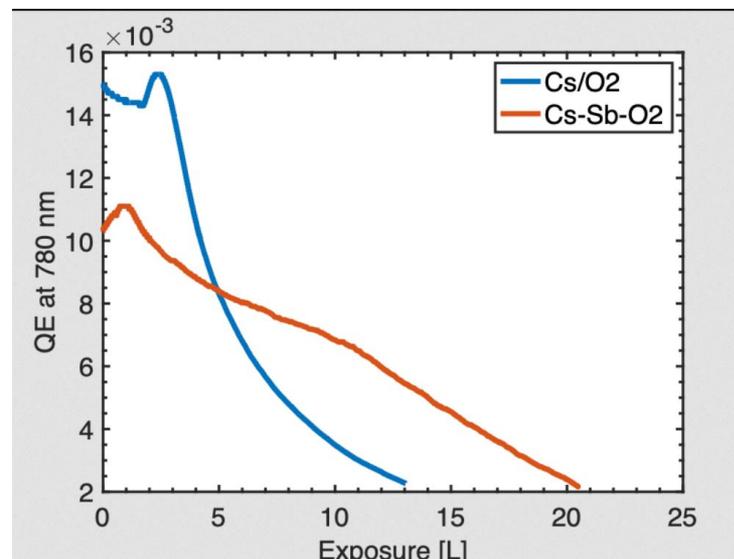




HERACLES growth chamber

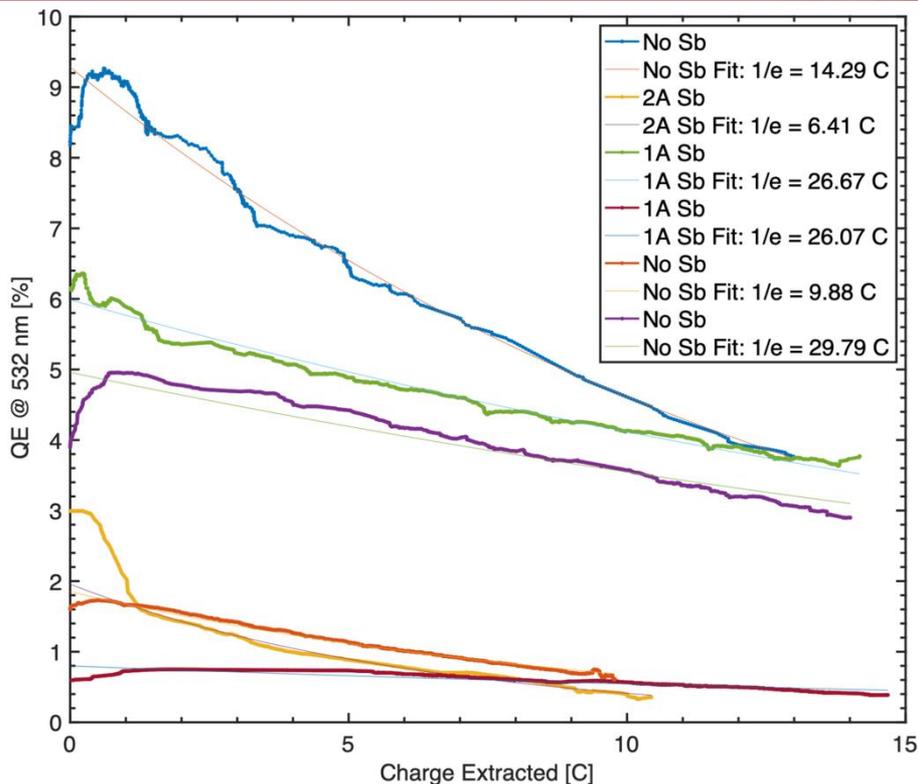


- Upgraded HERACLES to have an MBE growth chamber
- 3 Effusion cells (Cs, Sb, Te)+oxygen leak valve
- Reproduced Sb-based activation lifetime improvements in growth chamber
- Ready for high current runs!





Initial high current runs



On going campaign to determine optimal Sb thickness for operational lifetime improvement

- Average beam current of 1 mA operated at 532 nm
- 10-15 C of charge extracted per run
- More runs to come!

Sb Thickness (Angstrom)	0	0	0	1	1	2
Lifetime (C)	14.3	9.88	29.7	26.7	26.1	6.4



Thank you for your attention!



BACK UP SLIDES

- NEA GaAs can be generated by forming a heterojunction at the surface with another semiconductor (activation layer) subject to two criteria:
 - In the activation layer, the gap from the fermi level to vacuum should be **smaller** than GaAs's bandgap (~ 1.4 eV).
 - So that photoemission does not occur from activation layer, its bandgap should be **larger** than GaAs's.
 - This criteria can be violated if the activation layer is sufficiently thin
- The above suggest using p-doped GaAs with an intrinsic semiconductor with a small electron affinity for the activation layer
- Cs_3Sb and Cs_2Te can form the NEA heterojunction
 - Known to be less sensitive to chemical poisoning
 - As a photoemitters they are robust at high currents
 - This indicates Cs-Sb Cs-Te may be a very robust activation layers!**

